

Title (en)
A multilayer printed circuit board and a process for manufacturing the same

Title (de)
Mehrschichtige Leiterplatte und Verfahren zu ihrer Herstellung

Title (fr)
Carte de circuit imprimé multicouche et son procédé de fabrication

Publication
EP 1923489 A3 20090527 (EN)

Application
EP 08152454 A 19990914

Priority
• EP 06003717 A 19990914
• EP 99943326 A 19990914
• JP 25985498 A 19980914
• JP 28343598 A 19980917
• JP 28892598 A 19980924
• JP 33120098 A 19981120
• JP 33449998 A 19981125
• JP 36296298 A 19981221
• JP 9591699 A 19990402

Abstract (en)
[origin: EP1117283A1] A method for manufacturing a printed wiring board having a high-density wiring and a highly-reliable connection between conductor layers even if the annealing process is omitted because a conductor circuit made of an electroplating layer excellent in crystallinity and uniform electrodepositability and formed on a base sheet and a via hole are provided. The method comprising forming an interlayer resin insulating layer on a conductor wiring forming board, making an opening for making a via hole in the interlayer resin insulating layer, forming an electroless plating layer (1008) on the interlayer resin insulating layer, applying a resist film (1003) to the layer (1008), forming an electroplating film thereon, removing the resist film, and removing the electroless plating layer by etching so as to form a conductor wiring and a via hole characterized in that the electroless plating layer (1008) serves as a cathode, the plating metal serves as an anode, and electroplating is performed intermittently while maintaining the voltage between the anode and cathode at a constant value. <IMAGE>

IPC 8 full level
C23C 18/34 (2006.01); **C25D 5/18** (2006.01); **H05K 1/09** (2006.01); **H05K 3/10** (2006.01); **H05K 3/18** (2006.01); **H05K 3/46** (2006.01); **H05K 3/00** (2006.01); **H05K 3/24** (2006.01); **H05K 3/38** (2006.01); **H05K 3/42** (2006.01)

CPC (source: EP KR US)
C23C 18/1607 (2013.01 - EP US); **C23C 18/1653** (2013.01 - EP US); **C23C 18/22** (2013.01 - EP US); **C23C 18/30** (2013.01 - EP US); **C23C 18/34** (2013.01 - EP KR US); **C23C 18/405** (2013.01 - EP US); **C23C 18/54** (2013.01 - KR); **C23C 28/00** (2013.01 - EP US); **C23C 28/023** (2013.01 - EP US); **C23C 28/42** (2013.01 - EP US); **C25D 3/38** (2013.01 - EP US); **C25D 5/022** (2013.01 - EP US); **C25D 5/18** (2013.01 - EP US); **C25D 5/34** (2013.01 - EP US); **C25D 5/617** (2020.08 - EP US); **C25D 5/625** (2020.08 - EP US); **C25D 7/123** (2013.01 - EP US); **H05K 3/108** (2013.01 - EP US); **H05K 3/181** (2013.01 - EP US); **H05K 3/423** (2013.01 - EP US); **H05K 3/427** (2013.01 - EP US); **H05K 3/4602** (2013.01 - EP US); **H05K 3/4644** (2013.01 - EP US); **H01L 2224/16225** (2013.01 - EP US); **H01L 2924/15174** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H05K 3/0038** (2013.01 - EP US); **H05K 3/241** (2013.01 - EP US); **H05K 3/381** (2013.01 - EP US); **H05K 3/382** (2013.01 - EP US); **H05K 3/384** (2013.01 - EP US); **H05K 3/421** (2013.01 - EP US); **H05K 3/4652** (2013.01 - EP US); **H05K 3/4661** (2013.01 - EP US); **H05K 2201/0215** (2013.01 - EP US); **H05K 2201/0344** (2013.01 - EP US); **H05K 2201/0347** (2013.01 - EP US); **H05K 2201/09509** (2013.01 - EP US); **H05K 2201/09536** (2013.01 - EP US); **H05K 2201/09563** (2013.01 - EP US); **H05K 2201/0959** (2013.01 - EP US); **H05K 2201/096** (2013.01 - EP US); **H05K 2203/0353** (2013.01 - EP US); **H05K 2203/0723** (2013.01 - EP US); **H05K 2203/1476** (2013.01 - EP US); **H05K 2203/1492** (2013.01 - EP US); **Y10T 29/49126** (2015.01 - EP US); **Y10T 29/49128** (2015.01 - EP US); **Y10T 29/49155** (2015.01 - EP US); **Y10T 29/49156** (2015.01 - EP US); **Y10T 29/49165** (2015.01 - EP US)

Citation (search report)
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• [XY] JP H09199855 A 19970731 - SONY CORP
• [Y] JP H02182390 A 19900717 - CANON KK
• [A] EP 0727926 A2 19960821 - IBM [US]

Designated contracting state (EPC)
DE FI GB NL

DOCDB simple family (publication)
EP 1117283 A1 20010718; **EP 1117283 A4 20040623**; **EP 1117283 B1 20060510**; DE 69931272 D1 20060614; DE 69931272 T2 20070315; EP 1667504 A1 20060607; EP 1667504 B1 20120201; EP 1667505 A1 20060607; EP 1667506 A1 20060607; EP 1667506 B1 20120201; EP 1667507 A1 20060607; EP 1667507 B1 20120201; EP 1919266 A2 20080507; EP 1919266 A3 20090805; EP 1923488 A2 20080521; EP 1923488 A3 20090527; EP 1923489 A2 20080521; EP 1923489 A3 20090527; KR 100815668 B1 20080320; KR 20060101562 A 20060925; MY 128333 A 20070131; MY 144503 A 20110930; MY 144573 A 20111014; MY 144574 A 20111014; US 2004134682 A1 20040715; US 2007266886 A1 20071122; US 2009145652 A1 20090611; US 7230188 B1 20070612; US 7691189 B2 20100406; US 7827680 B2 20101109; US 8065794 B2 20111129; WO 0016597 A1 20000323

DOCDB simple family (application)
EP 99943326 A 19990914; DE 69931272 T 19990914; EP 06003704 A 19990914; EP 06003705 A 19990914; EP 06003716 A 19990914; EP 06003717 A 19990914; EP 08150255 A 19990914; EP 08152453 A 19990914; EP 08152454 A 19990914; JP 9905003 W 19990914; KR 20067018265 A 20060907; MY PI0501107 A 19990910; MY PI0501108 A 19990910; MY PI0501113 A 19990910; MY PI9903936 A 19990910; US 23930608 A 20080926; US 73649507 A 20070417; US 75142804 A 20040106; US 78713999 A 19990914